

Amendments to the Specification:

Submitted concurrently herewith is a substitute specification and marked up version thereof.

Please replace paragraph [0006] with the following amended paragraph:

[0006] On the other hand, epoxy resin and the like are used in the field of semiconductor device package, but there is used a method in which fine particles of silicon oxide (SiO_2) having a thermal expansion coefficient close to that of a device substrate (Si substrate) are added to a sealing resin material for the purpose of reducing thermal stress upon mounting onto a printed wiring board. However, in conventional technique, a plastic package of conventional structure using epoxy resin inferior to metal, ceramics, etc. in thermal conductivity is inferior in radiation characteristic and is quite high in thermal resistance. Therefore, it was disadvantageous in terms of a long-term reliability as an IC of high electric-power consumption such as power IC or as a package of IC operating at high speed. Furthermore, fine particles of SiO_2 added to resin to make it have low stress are very hard. Therefore, thermal stress generated upon mounting onto printed wiring board has added a large pressure locally to the device surface, thereby generating device destruction. In other words, there has been a demand for a material that is high in heat resistance and hardly adds thermal stress to the device surface in the field of semiconductor package (see Patent Publication 3). In fact, it is difficult to satisfy the demanded performances by a single semiconductor package material. Thus, various protecting films, etc. are used together. We can say that the package material and the protecting film are integrated and achieve their functions by compensating their respective weaknesses. A passivation film is used for preventing the intrusion of water and impurities into semiconductor chip, and a buffer coating film is used for loosening stress concentration occurring in a

package material. Hitherto, inorganic compounds such as silicon oxide have primarily been used for thin film materials, such as insulating film and protecting film, used for semiconductors. Nowadays, however, the usefulness of heat resistant polymer materials such as polyimide have been recognized, and they are used for ~~correlation~~ layer insulation film, passivation film, buffer coating film, etc. For the request of integration and high-speed of semiconductors in recent years, there is a demand for a material corresponding to the high-speed transmission of signals. In high-speed transmission, the propagation delay of signals becomes problematic, but it is effective to make a material have a lower dielectric constant since the propagation delay is proportional to relative dielectric constant of a material. Nowadays, it is known that fluororesins are low in dielectric constant, and fluorine-containing polyimide is also investigated as one of potential materials. A resin, into which fluorine atom has been introduced, has special properties possessed by fluorine, such as water repellency, non-adhesiveness, etc., and sometimes it can be utilized for the aimed use. Sometimes, however, its utilization was difficult due to its specificity. Along with the appearance of new semiconductor applied products in recent years, semiconductor packages have also been diversified. There have been various demands for them to be more compact, thinner, lower in dielectric constant, etc. A package material satisfying these has been demanded.

Patent Publication 1: Japanese Patent Laid-open Publication 10-161313

Patent Publication 2: Japanese Patent Laid-open Publication 2000-89463

Patent Publication 3: Japanese Patent Laid-open Publication 8-241913

Non-patent Publication 1: H. Ito, H. D. Truong, et al, J. Photopolym. Sci. Technol., 16, 523-536(2003)

Non-patent Publication 2: Francis Houlihan, Andrew Romano, Ralph R. Dammel, et al, J. Photopolym. Sci. Technol., 16, 581-590(2003)

Please replace paragraph [0025] with the following amended paragraph:

[0025] A polymer compound according to the present invention, which is characterized in that it contains a repeating unit having an acid-labile group is a polymer compound obtained by polymerization in a manner to contain a polymerizable monomer having an acid-labile group, or one obtained by replacing a part of a polymer compound with an acid-labile group. As examples of the acid-labile group, they can be used without particular limitation, as long as they are groups that generates elimination by the effect of photoacid generator, hydrolysis, etc. As specific examples are cited, it is possible to cite alkyloxyearbonylalkoxycarbonyl group, acetal group, silyl group, acyl group, etc. The alkoxycarbonyl group can be exemplified by tert-butoxycarbonyl group, tert-amyoxy carbonyl group, methoxycarbonyl group, ethoxycarbonyl group, i-propoxycarbonyl group and the like. As the acetal group, it is possible to cite methoxymethyl group, ethoxyethyl group, butoxyethyl group, cyclohexyloxyethyl group, benzyloxyethyl group, phenethyloxyethyl group, ethoxypropyl group, benzyloxypropyl group, phenethyloxypropyl group, ethoxybutyl group, ethoxyisobutyl group, etc. It is also possible to use an acetal group in which a vinyl ether has been added to the hydroxy group. As the silyl group, it is possible to cite, for example, trimethylsilyl group, ethyldimethylsilyl group, methylidimethylsilyl group, triethylsilyl group, i-propyldimethylsilyl group, methylid-i-propylsilyl group, tri-i-propylsilyl group, t-butylidimethylsilyl group, methylid-t-butylsilyl group, tri-t-butylsilyl group, phenyldimethylsilyl group, methylidiphenylsilyl group, triphenylsilyl group, and the like. As the acyl group, it is possible to cite acetyl group, propionyl group, butyryl group, heptanoyl group, hexanoyl group, valeryl group, pivaloyl group, isovaleryl group, lauryloyl group, myristoyl group, palmitoyl group, stearoyl group, oxalyl group, malonyl group, succinyl group, glutaryl group, adipoyl group, piperoyl group, suberoyl group, azelaoyl group, sebacoyl group, acryloyl group, propioloyl group, methacryloyl group, crotonoyl group, oleoyl group, maleoyl group, fumaroyl

group, mesaconoyl group, campholoyl group, benzoyl group, phthaloyl group, isophthaloyl group, terephthaloyl group, naphthoyl group, toluoyl group, hydratoropoyl group, atoropoyl group, cinnamoyl group, furoyl group, thenoyl group, nicotinoyl group, isonicotinoyl group, and the like. Furthermore, it is also possible to use ones in which fluorine atoms have been substituted for a part or entirety of hydrogen atoms of these acid labile groups.